

DemeFlux

6681 5070

**"RMA/ No clean" - flux on colophonium basis,
slightly activated, halogenfree, doseable**

DemeFlux 68105070 is activated regarding RMA (ANSI/J-STD-004: Flux type RO LO) and does not contain any types of halogens (halogenfree). It is suited as well for SM- as for hybrid application. An other application is soldering sheres at production of BGA components. Because of good temperature resistance it is also suited for high melting solder applications. Outstanding properties of the flux

are good wetting behaviour and excellent cleaning performance in current materials (e.g. terpenes...). The small flux residues can remain on solder joints because of passing SIR tests according to IPC-TM-650 and corrosion tests according ANSI/J-STD 004. The flux is suited for printing or dispenser applications because of deaerated and vacuum-packed cartridges and therefore free of air bubbles.

1. Flux properties

1.1 Flux type (ANSI/J-STD 004)

RMA, no clean Type RO LO

1.2 Flux appearance

creamy, yellowish, thixotrop

1.3 Flux smell

neutral

1.4 pH- value

4,7 - 4,9

1.5 Viscosity (Brookfield-Helipath, IPC-TM 650)

*250 Pa*s +/- 50 Pa*s*

1.6 Fineness of grain (Grindometer)

< 30 µm

1.7 Copper mirror (IPC-TM-650)

no breakthrough

1.8 Qualitative Halide (IPC-TM-650)

pass

1.9 Quantitative Halide (IPC-TM-650)

0.0 %

1.10 Corrosion Test (IPC-TM-650)

no evidence

1.11 SIR test (IPC-TM-650)

pass

1.12 Electromigration resistance test (TR-NWT-000078)

pass

2. Storage

12 months at room temperature

3. Containers

*Sealed polyethylene-containers at 0.5 kg, 1 kg or 2 kg
Sealed polyethylene syringes at 5 g, 10 g and 30 g
Special containers on request*

4. Application:

- *The flux paste exhibits no separation.*
- *Viscosity is optimized for dispensing systems, minimum diameter 0,25 mm.*
- *No predrying is necessary. If the flux is used for repairing, predrying at 150°C is recommended to prevent an explosive evaporating of solvents during the following solder step.*
- *Storage of printed boards up to 72 hours at room temperature and humidity up to 75 % does not influence the solder quality.*
- *Cleaning of flux residues is possible with CFC substitution products, e.g. terpenes as well as isopropyl alcohol assisted by ultrasonics.*
- *Please observe the working instructions of the cleaning solvents in use.*

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